

# Silicon Carbide Schottky Diode (SiC SBD)

## 1. Product Features:

- Revolutionary semiconductor material - Silicon Carbide
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Excellent thermal performance
- Specified dv/dt ruggedness
- Qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant

HDD06S065A

Pin 1 and backside – cathode  
Pin 2 – anode

Package: TO-252-2

## 2. Product Applications

- Solar Inverters
- Uninterruptable Power Supplies (UPS)
- Power Factor Correction (PFC)
- Switch Mode Power Supplies (SMPS)
- On Board Charger (OBC)
- EV Charger

## 3. Typical Performance Parameters

Tab.1. Typical Performance Parameters

Type	$V_{DC}$	$I_F$	$Q_C$	$T_{vjmax}$	Marking	Package
HDD06S065A	650V	6A	16nC	175°C	HDD06S065A	TO-252-2

## 4. Maximum Ratings

**Tab.2. Maximum Ratings**

Parameters	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	650	V
Surge Peak Reverse Voltage	$V_{RSM}$	650	V
Continuous Forward Current $T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$ $T_c = 150^\circ\text{C}$	$I_F$	40 13 6	A
Repetitive Peak Forward Surge Current $T_c = 25^\circ\text{C}, t_p = 10\text{ms}$	$I_{FRM}$	21	
Non-Repetitive Peak Forward Surge Current $T_c = 25^\circ\text{C}, t_p = 10\text{ms}, \text{Half Sine Wave}$	$I_{FSM}$	52	
Non-Repetitive Peak Forward Current $T_c = 25^\circ\text{C}, t_p = 10\mu\text{s}$	$I_{F, max}$	220	
Power Dissipation $T_c = 25^\circ\text{C}$ $T_c = 125^\circ\text{C}$ $T_c = 150^\circ\text{C}$	$P_{tot}$	83 28 14	W
Operating Junction	$T_j$	-55 to +175	°C
Storage Temperature	$T_{stg}$	-55 to +150	

## 5. Thermal Properties

**Tab.3. Thermal Properties**

Parameters	Symbol	Typ. value	Unit
Thermal resistance (junction - case)	$R_{th(j-c)}$	1.81	°C/W

## 6. Electrical Characteristics

Tab.4. Static Characteristic ( $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified)

Parameters	Symbol	Conditions	Min. value	Typ. value	Max. value	Unit
DC blocking voltage	$V_{DC}$	$T_j = 25^{\circ}\text{C}$	650	-	-	V
Diode forward voltage	$V_F$	$I_F = 6\text{A}, T_j = 25^{\circ}\text{C}$ $I_F = 6\text{A}, T_j = 175^{\circ}\text{C}$	- -	1.54 1.89	1.7 2.0	V
Reverse current	$I_R$	$V_R = 650\text{V}, T_j = 25^{\circ}\text{C}$ $V_R = 650\text{V}, T_j = 175^{\circ}\text{C}$	- -	1 3	5 30	$\mu\text{A}$

Tab.5. Dynamic Characteristic ( $T_{vj} = 25^{\circ}\text{C}$ , unless otherwise specified)

Parameters	Symbol	Conditions	Min. value	Typ. value	Max. value	Unit
Total capacitive charge	$Q_C$	$V_R = 400\text{V}, Q_C = \int_0^{V_R} C(V)dV$	-	16	-	nC
Total Capacitance	$C$	$V_R = 0\text{V}, f = 1\text{MHz}$ $V_R = 200\text{V}, f = 1\text{MHz}$ $V_R = 400\text{V}, f = 1\text{MHz}$	- - -	314 31 29	- - -	pF
Capacitance Stored Energy	$E_C$	$V_R = 400\text{V}$	-	4	-	$\mu\text{J}$

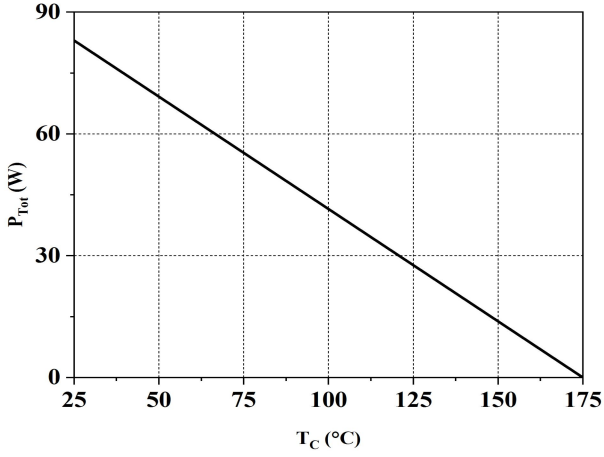


Fig.1. Power dissipation vs. case temperature

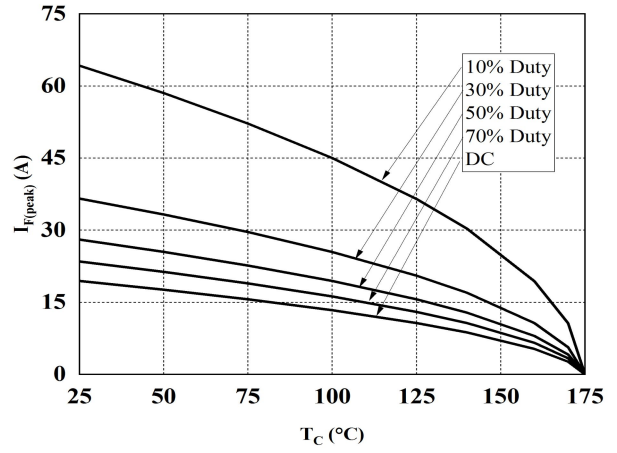


Fig.2. Diode forward current vs. case temperature

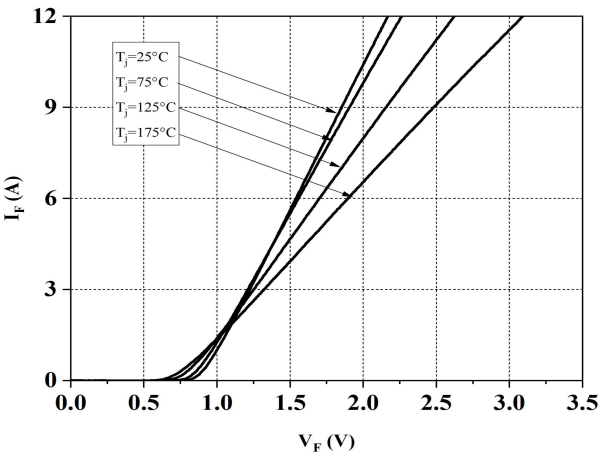


Fig.3. Typical forward characteristics

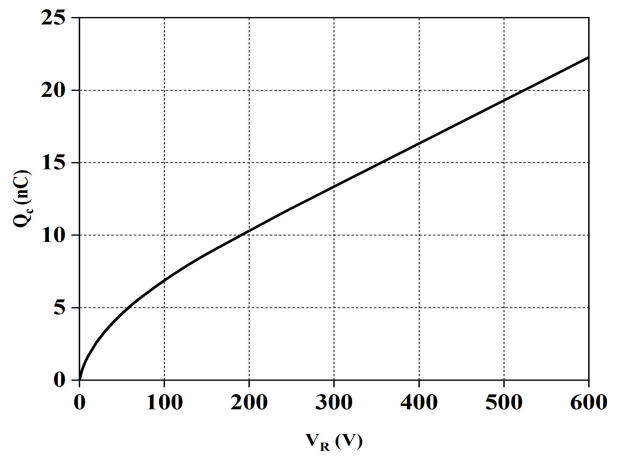


Fig.4. Typical capacitance charge vs. reverse voltage

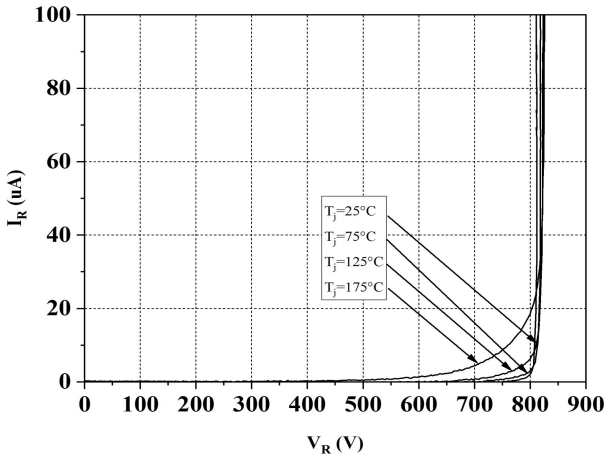


Fig.5. Typical reverse current vs. reverse voltage

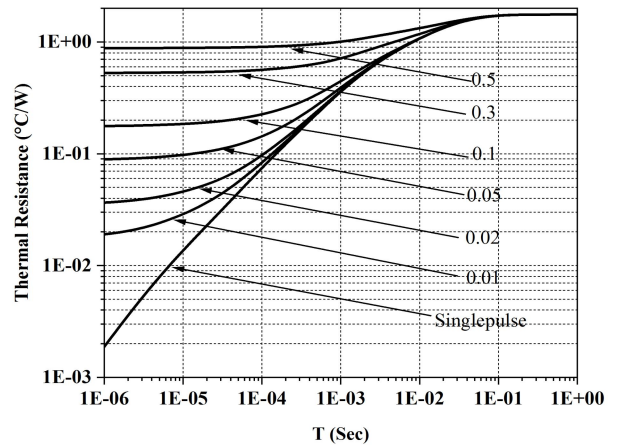


Fig.6. Max. transient thermal impedance

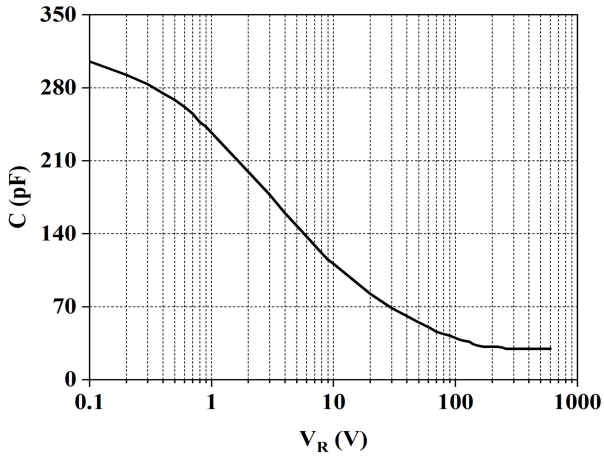


Fig.7. Typical capacitance vs. voltage

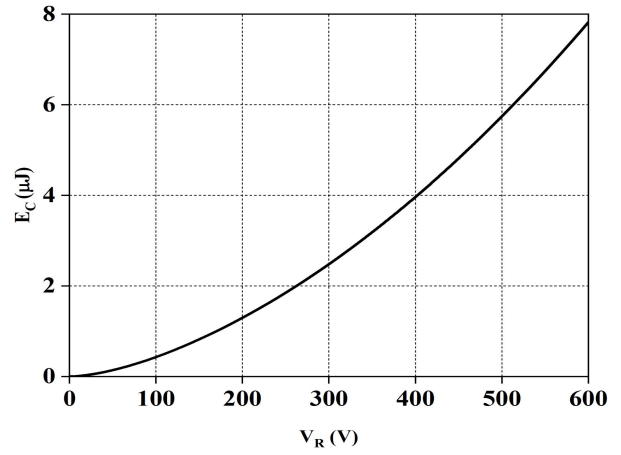
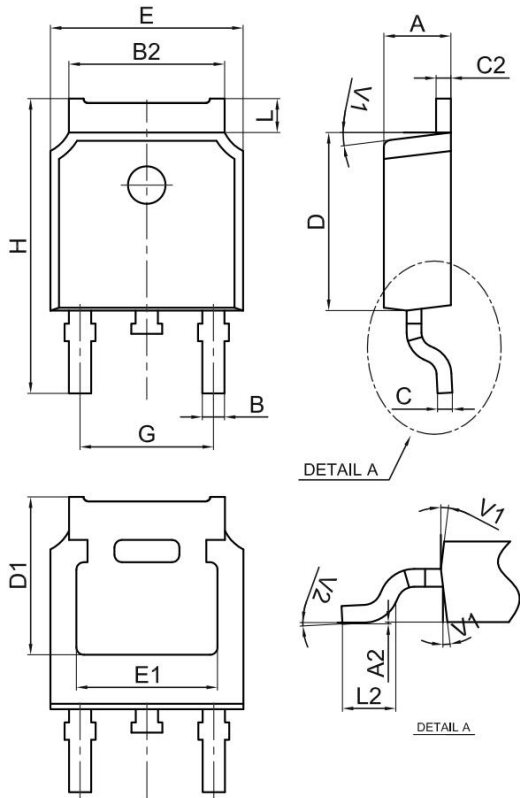


Fig.8. Typical capacitance stored energy vs. reverse voltage

### 7. Package Dimensions



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

## 8. Version Information

Version No.	Status	Date changed	Version revision record
V1.0	Preview edition	2022/01	
V1.1	Preview edition	2022/03	
V1.2	Preview edition	2022/07	